



Epoxy Bond 575 Technical Data Sheet

Epoxy Bond 575 is a single component epoxy adhesive designed to be used in applications where high temperatures and strong chemicals will be encountered. There is no mixing or proportioning required. The hardener is pre-weighed and added to the system. Epoxy Bond 575 has the lowest baking temperature and time requirements available, reducing oven time to maximize production. Not only does Epoxy Bond 575 have a very high deflection temperature, it has proven to bond extremely well to a wide variety of surfaces.

LIQUID PROPERTIES

Mix Ratio		None
System viscosity	cps	>15,000
Pot life @ room temperature	months	3
Cure Schedule	min@°F/°C	212/100
Followed by	min@°F/°C	250/121

CURED STATE PROPERTIES

Heat Deflection Temperature	°F/°C	230/110
Tensile Strength	psi	7,700
Tensile Elongation at break	%	2.2
Ultimate Compressive Strength	psi	36,000
Compressive Yield Strength	psi	18,800
Izod Impact, notched	ftlb/in	0.35
Hardness	Shore D	91